- Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- These assemblies are ESD sensitive, ESD precautions shall be observed.
- These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001
COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
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<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-00828</th>
<th>REV: E1</th>
<th>SUN REV: Not In VersionControl</th>
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<td></td>
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<td>GENERATED : 12/10/2015 12:17:36 PM</td>
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<td>TEXAS INSTRUMENTS</td>
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